Harvatek Surface Mount CHIP LEDs Data Sheet B26B3RGB-20C000213U1930

Official Product HT Part No. B26B3RGB-20C000213U1930					
Tentative Product	******	*****			
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DISCLAIMER
LIFE SUPPORT POLICY
PRODUCT SPECIFICATIONS4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION4
LABEL SPECIFICATIONS
SPECIFICATIONS RANGE
PRODUCT FEATURES
ELECTRO-OPTICAL CHARACTERISTICS8 PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW
Soldering
CHARACTERISTICS OF B26B3RGB9
PRECAUTION FOR USE10
PACKAGING11
PACKAGING
TAPE DIMENSION 11 REEL DIMENSION 12 PACKING 12
TAPE DIMENSION11REEL DIMENSION12PACKING12DRY PACK13
TAPE DIMENSION11REEL DIMENSION12PACKING12DRY PACK13BAKING13
TAPE DIMENSION11REEL DIMENSION12PACKING12DRY PACK13
TAPE DIMENSION11REEL DIMENSION12PACKING12DRY PACK13BAKING13
TAPE DIMENSION11REEL DIMENSION12PACKING12DRY PACK13BAKING13PRECAUTIONS13
TAPE DIMENSION 11 REEL DIMENSION 12 PACKING 12 DRY PACK 13 BAKING 13 PRECAUTIONS 13 REFLOW SOLDERING 14
TAPE DIMENSION 11 REEL DIMENSION 12 PACKING 12 DRY PACK 13 BAKING 13 PRECAUTIONS 13 REFLOW SOLDERING 14 Reworking 14
TAPE DIMENSION 11 REEL DIMENSION 12 PACKING 12 DRY PACK 13 BAKING 13 PRECAUTIONS 13 REFLOW SOLDERING 14 Reworking 14 CLEANING 14

7				
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 2/15

DISCLAIMER

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Life Support Policy

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7				
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 3/15

Product Specifications

Item	Specification	Material	Quantity
Luminous	R ÷ 28.5-180.0 mcd		
Intensity(Iv)	G:112.5-450.0 mcd		
	B:28.5-180.0 mcd		
	@20mA/ T_s = 25°C ;Tolerance:±10%		
Wavelength	R : 615.0-635.0 nm		
	G:515.0-540.0 nm		
	B:460.0-480.0 nm		
	@20mA/ T_s= 25 $^\circ\!\mathrm{C}$;Tolerance:±0.5nm		
Vf	R :1.6-2.4 V		
	G :2.7-3.9 V		
	B :2.7-3.9 V		
	@20mA/ T _S = 25 $^{\circ}$ C ;Tolerance:±0.05V		
lr	< 10 µA @ V _R = 5 V		
Resin	Clear	Ероху	
Carrier tape	EIA 481-1A specs	Conductive black tape	
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	250x230mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note :This is shipped test conditions

%Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



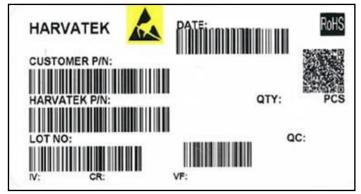
The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

7					
Official Product	HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	******	****			
	t to changes for improvement without advance rawings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 4/15	

Label Specifications



Harvatek P/N:

В	26B	3	RGB-	20C-	0002	13
Product	Package	Dice Qty	Color	Current	Series Number	Taping
PCB	3.2(L)x1.2(W)x0.8(H) mm	3: Tri	FCH: RGB	20mA	X001~XZZZ	1.Taping style
			(Full Color)			2. Qty

Lot No.:

1	2	3	4	5	6	7	8	9	10
E	1	Α	1	Α	2	2	L	1	2
Code	12	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	2
Internal Tra	cing Code	2020-L 2021-M 2022-P 2023-Q 2026-T 2027-V 2030-Y 2031-Z 	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000~ZZZ	

Official Product	HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	***************************************				
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 5/15	

Specifications Range

Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
	Ν	28.50-45.00 mcd
B	Р	45.00-71.50 mcd
n	Q	71.50-112.5 mcd
	R	112.5-180.0 mcd
	R	112.5-180.0 mcd
0	S	180.0-285.0 mcd
G	Т	285.0-360.0 mcd
	U	360.0-450.0 mcd
	N	28.50-45.00 mcd
В	Р	45.00-71.50 mcd
в	Q	71.50-112.5 mcd
	R	112.5-180.0 mcd

Note: It maintains a tolerance of ±10% on luminous intensity

Wavelength Bin:

Color	Bin Code	Spec. Range
R	AD 615.0-635.0 nm	
	Α	515.0-520.0 nm
G	В	520.0-525.0 nm
	С	525.0-530.0 nm
	D	530.0-535.0 nm
	E	535.0-540.0 nm
	AA	460.0-465.0 nm
В	AB	465.0-470.0 nm
D	AC	470.0-475.0 nm
	AD	475.0-480.0 nm

Note: It maintains a tolerance of \pm 0.5nm on Wavelength bin

7				
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 6/15

Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
R	E18	1.6-2.4 V
	G8	2.7-2.9 V
	H7	2.9-3.1V
G	H8	3.1-3.3 V
G	J7	3.3-3.5 V
	J8	3.5-3.7 V
	K7	3.7-3.9 V
	G8	2.7-2.9 V
	H7	2.9-3.1V
В	H8	3.1-3.3 V
0	J7	3.3-3.5 V
	J8	3.5-3.7 V
	K7	3.7-3.9 V

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

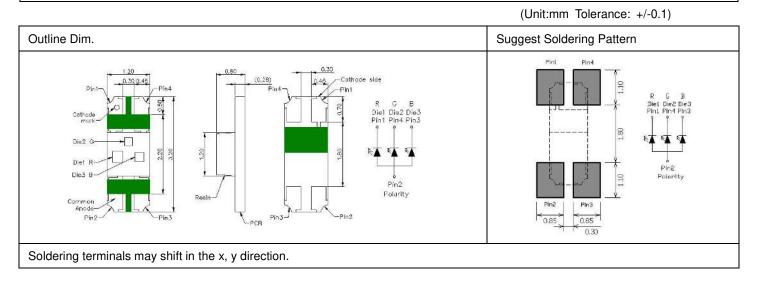
7				
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	***************************************			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 7/15

Product Features

Electro-Optical Characteristics

			-					(T _{Solde}	ering , 25 °C)
Series	Emitting Color	V _F (V)		Wavelength $\lambda(nm)$			I _V (mcd)	Viewing	
Series	Emitting Color	Material	typ	max	λ_{D}	λ_{P}	Δλ	Typical	Angle $2\theta \frac{1}{2}$
	R	AlGaInP	2.0	2.4	624 (633	632 20	71.5	X=120
	n	AlGainF	2.0	2.4	024	032			Y=120
B26B3RGB-20	G	InGaN	3.3	3.9	525	525 520	520 30	285.0	X=145
D20D3NGD-20	G	Indan	5.5	5.5	525	520	50	205.0	Y=155
	В	InGaN	3.3	3.9	470	468	40	71.5	X=140
	d	maan	5.5	5.9	470	400	40	71.5	Y=125

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering



Absolute Maximum Ratings

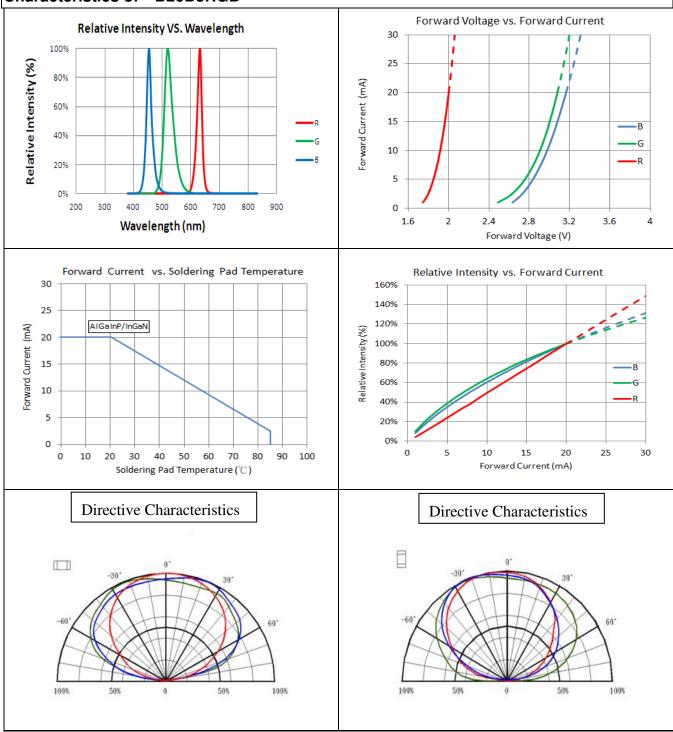
(T_{Soldering} 25 ℃)

	(ISoldering ZS C)					
Series	P _D (mW)	I _F (mA)	I _{FP} (mA)*	Т _{ОР} (℃)	Т _{sт} (°С)	
Color	Power Dissingtion	Forward Current	Pulse Forward	Operating	Storage	
Color	olor Power Dissipation Forward Current	Current	Temperature	Temperature		
R	48	20	100	-40~+85	-40~+100	
G	78	20	80	-40~+85	-40~+100	
В	78	20	80	-40~+85	-40~+100	

*Condition for I_{FP} is pulse of 1/10 duty and 0.1 msec width

7					
Official Product	HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	*****	*****			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 8/15	

Characteristics of B26B3RGB



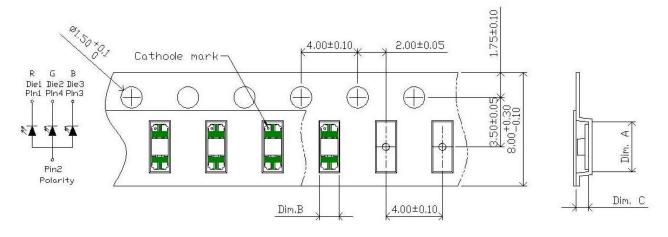
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	***************************************			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 9/15

Precaution for Use

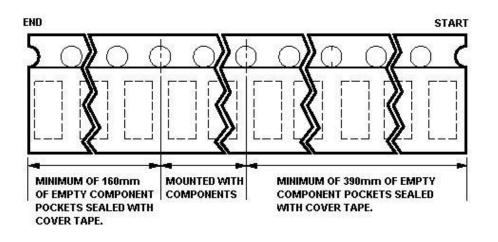
- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

7				
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	***************************************			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 10/15

Packaging Tape Dimension

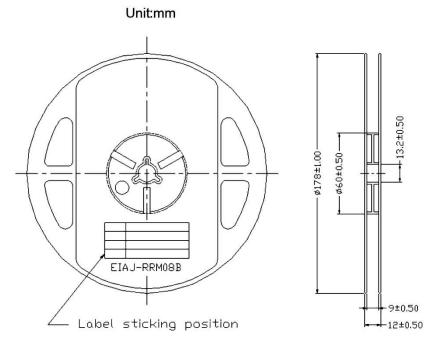


Dim. A	Dim. B	Dim. C	Qty/Reel
3.55±0.05	1.35±0.05	0.88±0.05	ЗK

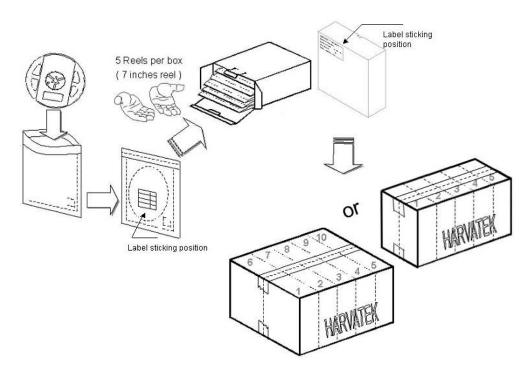


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Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	***************************************			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 11/15

Reel Dimension



Packing



5 or 10 boxes per carton is available depending on shipment quantity.

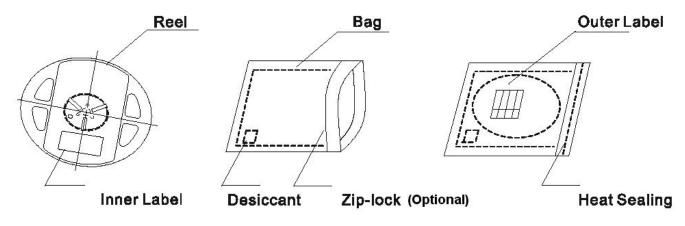
Official Product	HT Part No. B26B3RGB-20C000213U1930			
Tentative Product	*********			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 12/15

Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 4 weeks. The conditions are as followings:

- 1. $60\pm3^{\circ}C\times(12\sim24hrs)$ and <5% RH, taped reel type.
- 2. 100±3°C ×(45min~1hr), bulk type.
- 3. $130\pm3^{\circ}C \times (15\min \sim 30\min)$, bulk type.

Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

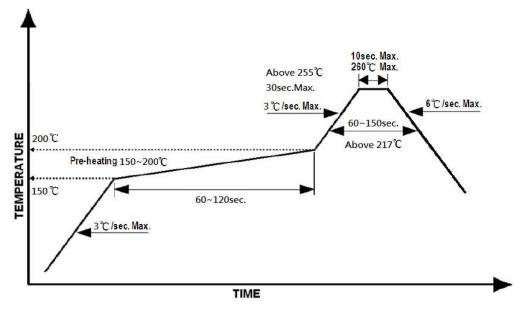
Official Product	HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	*****	*******			
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 13/15	

Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217° C ,60~150 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260 $^\circ C$.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50° C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 $^{\circ}$ C max, <3min

Official Product	HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	*********				
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 14/15	

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

Rev.	Descriptions	Date	Page
1.0	-	03/26/2015	-
1.1	Renew form	10/20/2015	-
1.2	Renew form	06/06/2017	-
1.3	Renew form	05/02/2018	-
1.4	Renew form	03/09/2020	-
1.5	Renew form	08/18/2022	-

Official Product HT Part No. B26B3RGB-20C000213U1930				
Tentative Product	*****	*****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	08/18/2022	Version 1.5	Page 15/15